

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A structure comprising:

a buried cavity in a semiconductor material body having a shape, in cross section, in which a top wall, including a lattice having a first and a second layer, is approximately parallel with a horizontal plane of the semiconductor material body, side walls slope inward from the top wall to a bottom wall, and the bottom wall is approximately parallel with the top wall.

2. (Currently Amended) The structure according to claim 1, wherein ~~the top wall comprises a lattice of a first and a second layer~~, said first layer comprising comprises silicon-dioxide, and said second layer comprising comprises silicon-nitride.

3. (Currently Amended) The structure according to claim 2, wherein said lattice has a plurality of interstitial openings.

4. (Original) The structure according to claim 3, wherein said plurality of interstitial openings in the lattice are filled with tetraethyl orthosilicate.

5. (Original) The structure according to claim 3, wherein said plurality of interstitial openings in the lattice are filled with polycrystalline silicon.

6. (Currently Amended) The structure according to claim 5, wherein said top wall of said buried cavity further comprises a grown layer, and wherein communication openings extend through said grown epitaxial layer and said lattice layer to said buried cavity.

7. (Original) The structure according to claim 3, wherein each of said plurality of interstitial openings has a square shape, as viewed from above the horizontal plane of the semiconductor material body.

8. (Original) The structure according to claim 3, wherein each of said plurality of interstitial openings has a rectangular shape, as viewed from above the horizontal plane of the semiconductor material body.

9. (Currently Amended) The structure according to claim 21, wherein said lattice is oriented to an angle of between 44° and 46° with respect to a flat of said semiconductor material body.

10. (Currently Amended) The structure according to claim 21, wherein said lattice is oriented to an angle of between 30° and 60° with respect to a particular crystallographic plane of said semiconductor material body.

11. (Cancelled)

12. (Currently Amended) The structure of claim 11-13 wherein the cover further comprises a lattice layer formed on the upper surface of the body.

13. (Currently Amended) A structure, comprising:
a semiconductor material body;
a cavity formed within the body, the cavity having a substantially planar lower surface lying in a plane that is approximately parallel to a plane of an upper surface of the body;
a cover over the cavity comprising a ~~The structure of claim 11 wherein the coating layer is a polycrystalline-silicon coating layer formed on the upper surface of the body;~~
and
a communication opening extending in the cover as far as the cavity.

14. (Original) The structure of claim 13, further comprising a layer grown on the polycrystalline-silicon layer.

15. (Currently Amended) A structure, comprising:
a semiconductor material body;
a cavity formed within the body[,];
a cover over the cavity comprising a lattice layer having a plurality of openings, formed on an upper surface of the body, and a coating layer formed on the lattice layer, the coating layer closing the plurality of openings; and

a communication opening extending through the coating layer in the cover as far as the cavity.

16. (Original) The structure of claim 15 wherein the coating layer is a polycrystalline-silicon layer.

17. (Original) The structure of claim 16, further comprising a layer grown on the polycrystalline-silicon layer.